Abstracts

Solder Free Interconnects for Mixed Signal (DC/Microwave) Systems

D. Strack, H. Fudem, F. Kuss, W. Marsh and J. Costello. "Solder Free Interconnects for Mixed Signal (DC/Microwave) Systems." 1996 MTT-S International Microwave Symposium Digest 96.1 (1996 Vol. I [MWSYM]): 231-234.

A method of achieving high density interconnections is demonstrated through the use of solder free interconnects, between multilayer substrates in which a common technology can be used for both microwave and DC interconnects of large electronic systems.

❑ Return to main document.